



Material Content Data Sheet



Sales Product Name				ESD5V3U4U-HDMI E6327		Issued		29. August 2013	
MA#				MA000491226					
Package				PG-TSLP-9-1		Weight*		1.58 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.001	0.09		882		
	noble metal	gold	7440-57-5	0.005	0.34		3420		
	inorganic material	silicon	7440-21-3	0.040	2.53	2.96	25341	29643	
leadframe	non noble metal	nickel	7440-02-0	0.330	20.89	20.89	208863	208863	
wire	noble metal	gold	7440-57-5	0.043	2.72	2.72	27161	27161	
encapsulation	organic material	carbon black	1333-86-4	0.011	0.68		6814		
	plastics	epoxy resin	-	0.146	9.20		91992		
	inorganic material	silicondioxide	60676-86-0	0.922	58.26	68.14	582612	681418	
leadfinish	noble metal	gold	7440-57-5	0.032	2.01	2.01	20097	20097	
plating	noble metal	silver	7440-22-4	0.052	3.28	3.28	32818	32818	
*deviation	< 10%					Sum in total:	100,00	1000000	

Important Remarks:

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